

	TSD3G
Taiwan	Semiconductor



FEATURES

• High ESD capability

TAIWAN

• Glass passivated chip junction

SEMICONDUCTOR

- Ideal for automated placement
- Low forward voltage drop
- High surge current capability
- Moisture sensitivity level: level 1, per J-STD-020
- AEC-Q101 qualified available: ordering code with suffix "H"
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Switching mode power supply (SMPS)
- Adapters
- Lighting application
- Converter

MECHANICAL DATA

- Case: DO-214AB (SMC)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.21 g (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
I _{F(AV)}	3	А		
V _{RRM}	400	V		
I _{FSM}	100	Α		
V _F at I _F =3A	1	V		
T _{J MAX}	175	°C		
Package	DO-214AB (SMC)			
Configuration	Single die			





DO-214AB (SMC)

SOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)				
PARAMETER	SYMBOL	TSD3G	UNIT	
Marking code on the device		TSD3G		
Repetitive peak reverse voltage	V _{RRM}	400	V	
Reverse voltage, total rms value	V _{R(RMS)}	280	V	
Forward current	I _{F(AV)}	3	А	
Surge peak forward current, 8.3 ms single half sine-wave superimposed on rated load per diode	I _{FSM}	100	А	
Junction temperature	TJ	- 55 to +175	°C	
Storage temperature	T _{STG}	- 55 to +175	°C	

1



THERMAL PERFORMANCE					
PARAMETER	SYMBOL	ТҮР	UNIT		
Junction-to-lead thermal resistance	R _{θJL}	21	°C/W		
Junction-to-ambient thermal resistance	R _{eja}	59	°C/W		
Junction-to-case thermal resistance	R _{eJC}	22	°C/W		

Thermal Performance Note: Units mounted on PCB (16mm x 16mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	ТҮР	MAX	UNIT
Forward voltage per diode ⁽¹⁾	I _F = 1.5A, T _J = 25°C		0.85	0.95	V
	I _F = 3A, T _J = 25°C	V _F	0.89	1.00	V
	I _F = 1.5A, T _J = 125°C		0.72	0.90	V
	I _F = 3A, T _J = 125°C		0.76	1.00	V
Reverse current @ rated $V_R^{(2)}$	T _J = 25°C	- I _R	-	1	μA
	T _J = 125°C		-	50	μA
Junction capacitance	1 MHz, V _R =4.0V	CJ	45	-	pF

Notes:

1. Pulse test with PW=0.3 ms

2. Pulse test with PW=30 ms

MMUNITY TO ELECTRICAL STATIC DISCHARGE TO THE FOLLOWING STANDARDS (T _A = 25°C unless otherwise noted)						
Standard	Test Type	Test Conditions	SYMBOL	CLASS	Value	Typical
AEC-Q101-001	Human body model(contact mode)	C=100pF,R=1.5kΩ	Vc	H3B	≥8kV	N/A
	Contact mode	C=150pF,R=330Ω		4	≥8kV	25kV
IEC 61000-4-2	Air-discharge mode	C=150pF,R=330Ω		4	≥15kV	30kV
	Contact mode	C=330pF,R=330Ω		L4	≥15kV	25kV
ISO 10605	Air-discharge mode	C=330pF,R=330Ω		L4	≥25kV	30kV



ORDERING INFORMATION				
ORDERING CODE (Note 1)	PACKAGE	PACKING		
TSD3GHR7G	SMC	850 / 7" Plastic reel		
TSD3GHR6G	SMC	3,000 / 13" Paper reel		
TSD3GHM6G	SMC	3,000 / 13" Plastic reel		
TSD3G R7G	SMC	850 / 7" Plastic reel		
TSD3G R6G	SMC	3,000 / 13" Paper reel		
TSD3G M6G	SMC	3,000 / 13" Plastic reel		

Note:

1. "H" means AEC-Q101 qualified



INSTANTANEOUS REVERSE CURRENT (µA)

CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

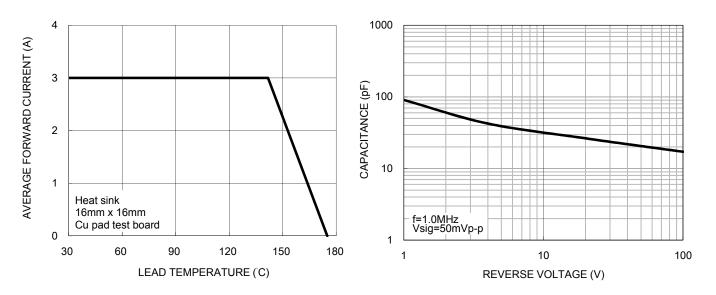
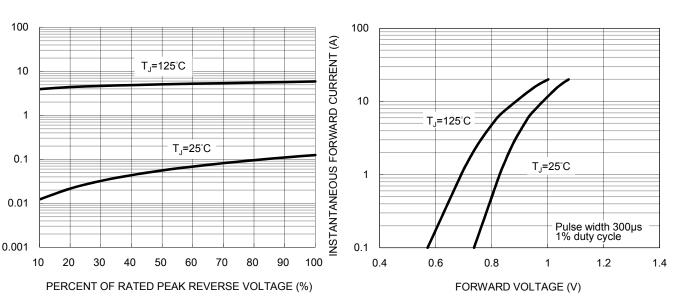


Fig.1 Forward Current Derating Curve

Fig.2 Typical Junction Capacitance

Fig.3 Typical Reverse Characteristics

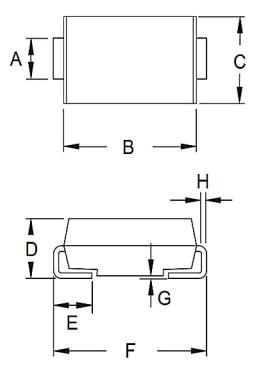
Fig.4 Typical Forward Characteristics





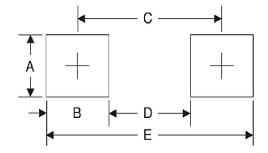
PACKAGE OUTLINE DIMENSIONS

DO-214AB (SMC)



DIM.	Unit (mm)		Unit	(inch)	
DIN.	Min	Max	Min	Max	
А	2.90	3.20	0.114	0.126	
В	6.60	7.11	0.260	0.280	
С	5.59	6.22	0.220	0.245	
D	2.00	2.62	0.079	0.103	
E	1.00	1.60	0.039	0.063	
F	7.75	8.13	0.305	0.320	
G	0.10	0.20	0.004	0.008	
Н	0.15	0.31	0.006	0.012	

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	3.30	0.130
В	2.50	0.098
С	6.80	0.268
D	4.40	0.173
E	9.40	0.370

MARKING DIAGRAM



- P/N =Marking Code
- G =Green Compound
- YW =Date Code
- F =Factory Code



Notice

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf, assumes no responsibility or liability for any errors or inaccuracies.

Purchasers are solely responsible for the choice, selection, and use of TSC products and TSC assumes no liability for application assistance or the design of Purchasers' products.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.